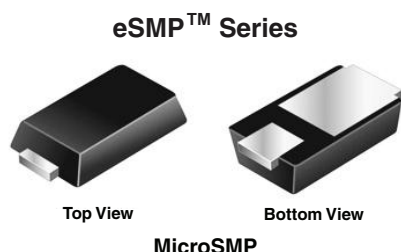


Surface Mount Schottky Barrier Rectifiers



PRIMARY CHARACTERISTICS

| | |
|------------------------|------------|
| $I_{F(AV)}$ | 2 A |
| V_{RRM} | 20 V, 30 V |
| I_{FSM} | 30 A |
| V_F at $I_F = 2.0$ A | 0.47 V |
| T_J max. | 150 °C |

TYPICAL APPLICATIONS

For use in low voltage high frequency inverters, freewheeling, dc-to-dc converters, and polarity protection applications.

FEATURES

- Very low profile - typical height of 0.68 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency
- “Green” molding compound (GMC)
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



RoHS
COMPLIANT

MECHANICAL DATA

Case: MicroSMP

Molding compound meets UL 94V-0 flammability rating.

“G” vs. “E” suffix defines molding as none green, “E”, or green molding compound (GMC) “G”.

“G” is defined as halogen-free (HF) and antimony-free molding compound that is < 50 ppm for F, Cl, Br, I and At, and < 5 ppm for Sb.

Note:

- There is no industry standard for definition of HF, or GMC for components.

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102

E3 suffix for consumer grade, meets JESD 201 class 1A whisker test. “E3” terminal finish per J-STD-609

Polarity: Color band denotes the cathode end

MAXIMUM RATINGS ($T_A = 25$ °C unless otherwise noted)

| PARAMETER | SYMBOL | MSS2P2 | MSS2P3 | UNIT |
|--|----------------|---------------|--------|------|
| Device marking code | | 22 | 23 | |
| Maximum repetitive peak reverse voltage | V_{RRM} | 20 | 30 | V |
| Maximum average forward rectified current (Fig. 1) | $I_{F(AV)}$ | 2.0 | | A |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | I_{FSM} | 30 | | A |
| Operating junction and storage temperature range | T_J, T_{STG} | - 55 to + 150 | | °C |

ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | SYMBOL | TYP. | MAX. | UNIT |
|--|----------------------|---|--------|-----------|-----------|---------------------|
| Maximum instantaneous forward voltage ⁽¹⁾ | $I_F = 1.0\text{ A}$ | $T_A = 25\text{ }^{\circ}\text{C}$ | V_F | 0.44 | - | V |
| | $I_F = 2.0\text{ A}$ | | | 0.52 | 0.60 | |
| | $I_F = 1.0\text{ A}$ | $T_A = 125\text{ }^{\circ}\text{C}$ | | 0.36 | - | |
| | $I_F = 2.0\text{ A}$ | | | 0.47 | 0.55 | |
| Maximum reverse current ⁽¹⁾ | rated V_R | $T_A = 25\text{ }^{\circ}\text{C}$ $T_A = 125\text{ }^{\circ}\text{C}$ | I_R | 15 6.0 | 250 20 | μA mA |
| Typical junction capacitance | 4.0 V, 1 MHz | | C_J | 65 | - | pF |

Note:(1) Pulse test: 300 μs pulse width, 1 % duty cycle**THERMAL CHARACTERISTICS** ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

| PARAMETER | SYMBOL | MSS2P2 | MSS2P3 | UNIT |
|---|-----------------|--------|--------|----------------------|
| Typical thermal resistance ⁽¹⁾ | $R_{\theta JA}$ | 105 | | $^{\circ}\text{C/W}$ |
| | $R_{\theta JL}$ | 15 | | |
| | $R_{\theta JC}$ | 20 | | |

Note:(1) Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 6.0 x 6.0 mm copper pad areas. $R_{\theta JL}$ is measured at the terminal of cathode band. $R_{\theta JC}$ is measured at the top center of the body**ORDERING INFORMATION** (Example)

| PREFERRED P/N | UNIT WEIGHT (g) | PREFERRED PACKAGE CODE | BASE QUANTITY | DELIVERY MODE |
|---------------|-----------------|------------------------|---------------|-----------------------------------|
| MSS2P3-E3/89A | 0.006 | 89A | 4500 | 7" diameter plastic tape and reel |
| MSS2P3-G3/89A | 0.006 | 89A | 4500 | 7" diameter plastic tape and reel |

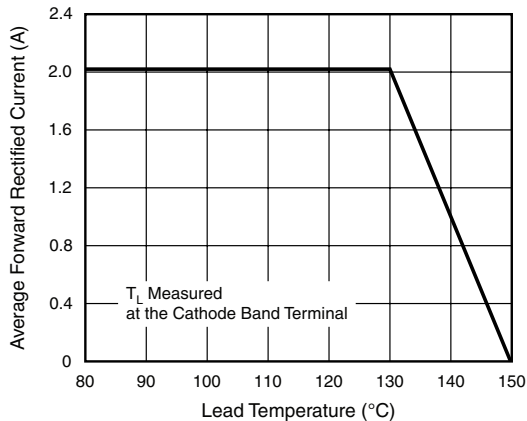
RATINGS AND CHARACTERISTICS CURVES($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

Figure 1. Forward Current Derating Curve

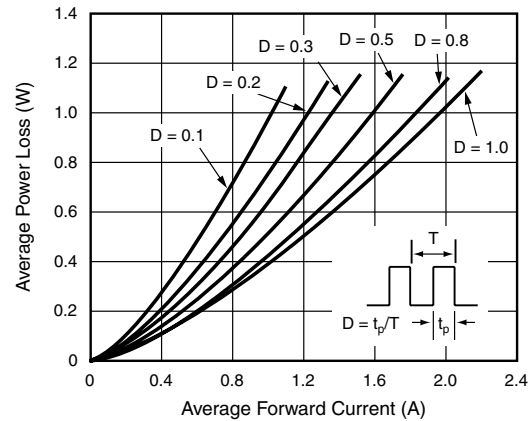


Figure 2. Forward Power Loss Characteristics

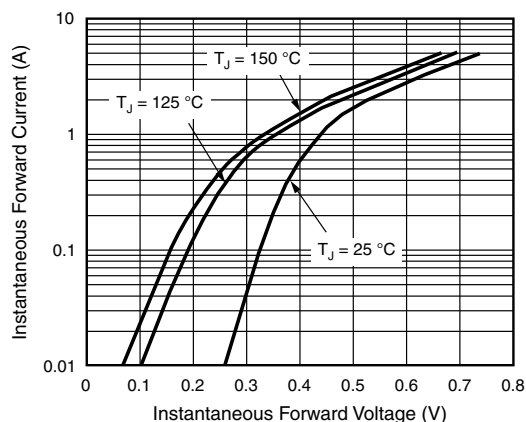


Figure 3. Typical Instantaneous Forward Characteristics

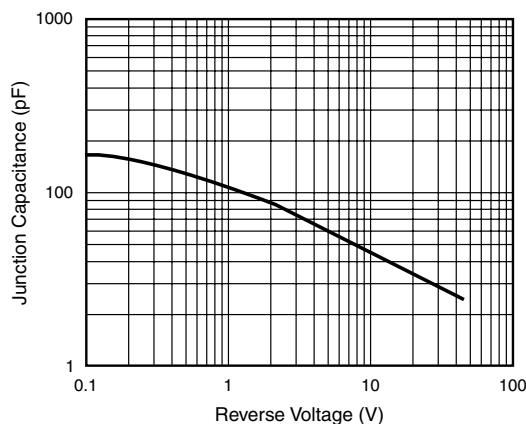


Figure 5. Typical Junction Capacitance

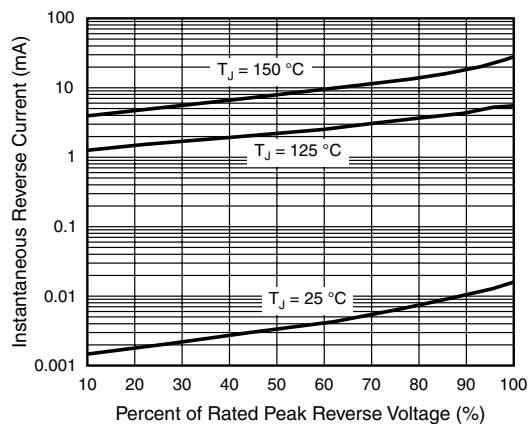


Figure 4. Typical Reverse Characteristics

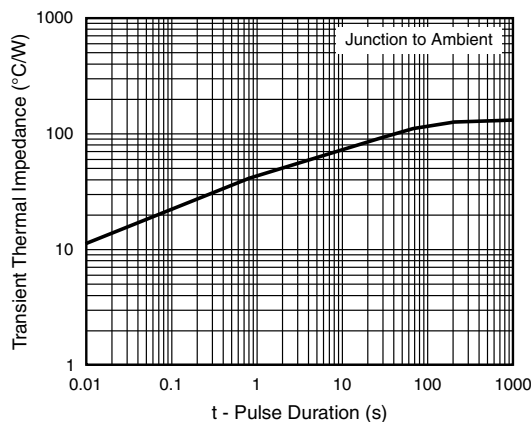
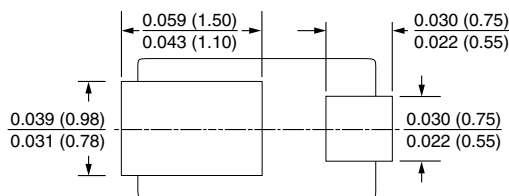
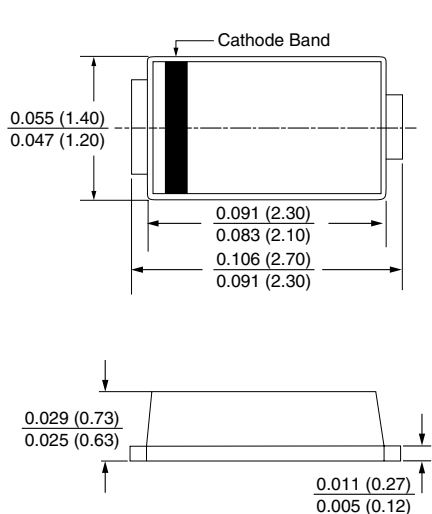


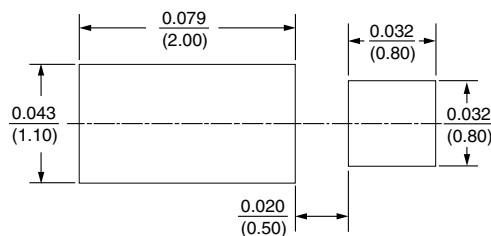
Figure 6. Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

MicroSMP



Mounting Pad Layout





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